MT0630S

N-Channel Enhancement Mode Field Effect Transistor

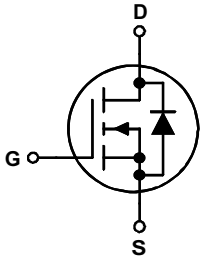
MT Semiconductor®

http://www.mtsemi.com

Features

- 60V,25A
- $R_{DS(ON)}$ = 25mΩ (Typ.) @ V_{GS} = 10V
- $R_{DS(ON)}$ = 35Ω (Typ.) @ V_{GS} = 4.5V
- Low Total Gate Charge
- Low Reverse Transfer Capacitance
- Improved dv/dt Capability
- Fast Switching Speed

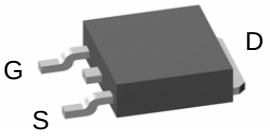
Simplified Schematic



MARKING DIAGRAM & PIN ASSIGNMENT

Application

- Uninterruptible Power Supply(UPS)
- Inverter System



D-PAK
TO-252-2L

Absolute Maximum Ratings (T_C=25℃ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		60	V
V_{GSS}	Gate-Source Voltage		±20	V
I_D	Continuous Drain Current	T_C = 25℃	25	A
		T_C = 100℃	18	A
I_{DM}	Pulsed Drain Current note1		85	A
P_D	Power Dissipation	T_C = 25℃	30	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		5	℃/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		50	℃/W
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	℃

Electrical Characteristics (T_C=25℃ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V,I_D=250μA	60	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} =60V, V_{GS} = 0V, T_J= 25℃	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	V_{DS} =0V,V_{GS} = ±20V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}= V_{GS}, I_D=250μA	0.7	1.2	2.0	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note2	V_{GS} =10V, I_D =20A	-	25	30	mΩ
		V_{GS} =4.5V, I_D =10A	-	35	40	mΩ
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 30V, V_{GS} = 0V, f = 1.0MHz	-	800	-	pF
C_{oss}	Output Capacitance		-	68	-	pF
C_{rss}	Reverse Transfer Capacitance		-	36	-	pF
Q_g	Total Gate Charge	V_{DS} =10V, I_D =30A, V_{GS} = 10V	-	15	-	nC
Q_{gs}	Gate-Source Charge		-	2.4	-	nC
Q_{gd}	Gate-Drain(“Miller”) Charge		-	2.5	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	V_{GS}=10V, V_{DS}=30V, R_L=1.0Ω, R_{REN} =3Ω,	-	5	-	ns
t_r	Turn-on Rise Time		-	39	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	19	-	ns
t_f	Turn-off Fall Time		-	7	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	25	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	85	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS} = 0V, I_S=10A	-	-	1.2	V
t_{rr}	Reverse Recovery Time	V_{GS} =0V, I_S=20A, di/dt=500A/μs	-	23	-	ns
Q_{rr}	Reverse Recovery Charge		-	45	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

Typical Performance Characteristics

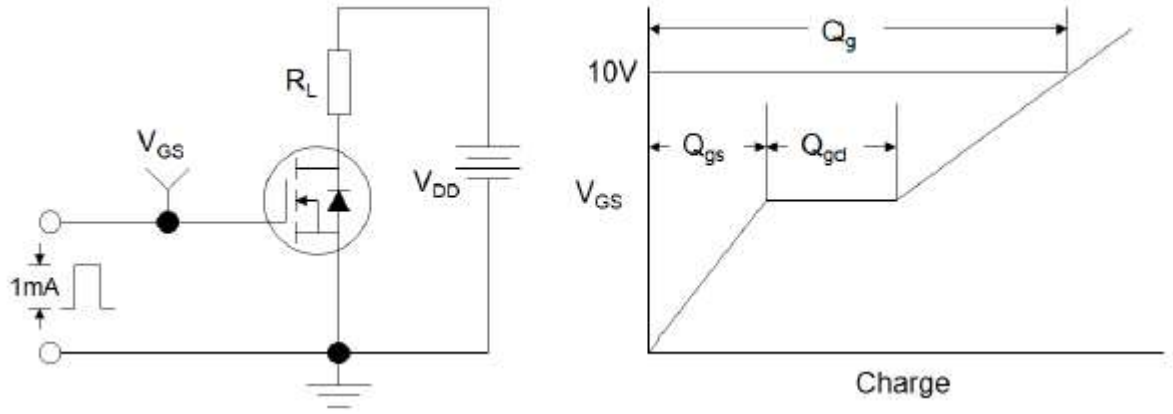


Figure1:Gate Charge Test Circuit & Waveform

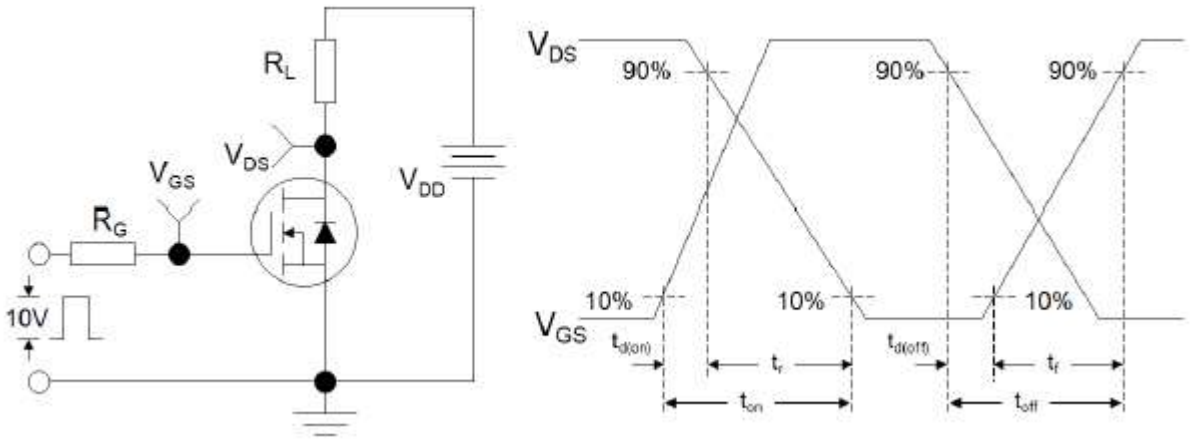


Figure 2: Resistive Switching Test Circuit & Waveforms

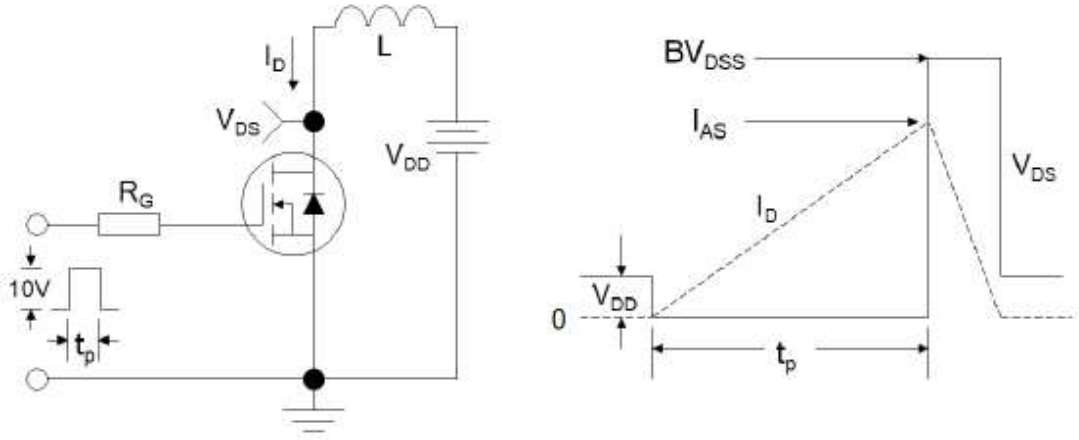


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

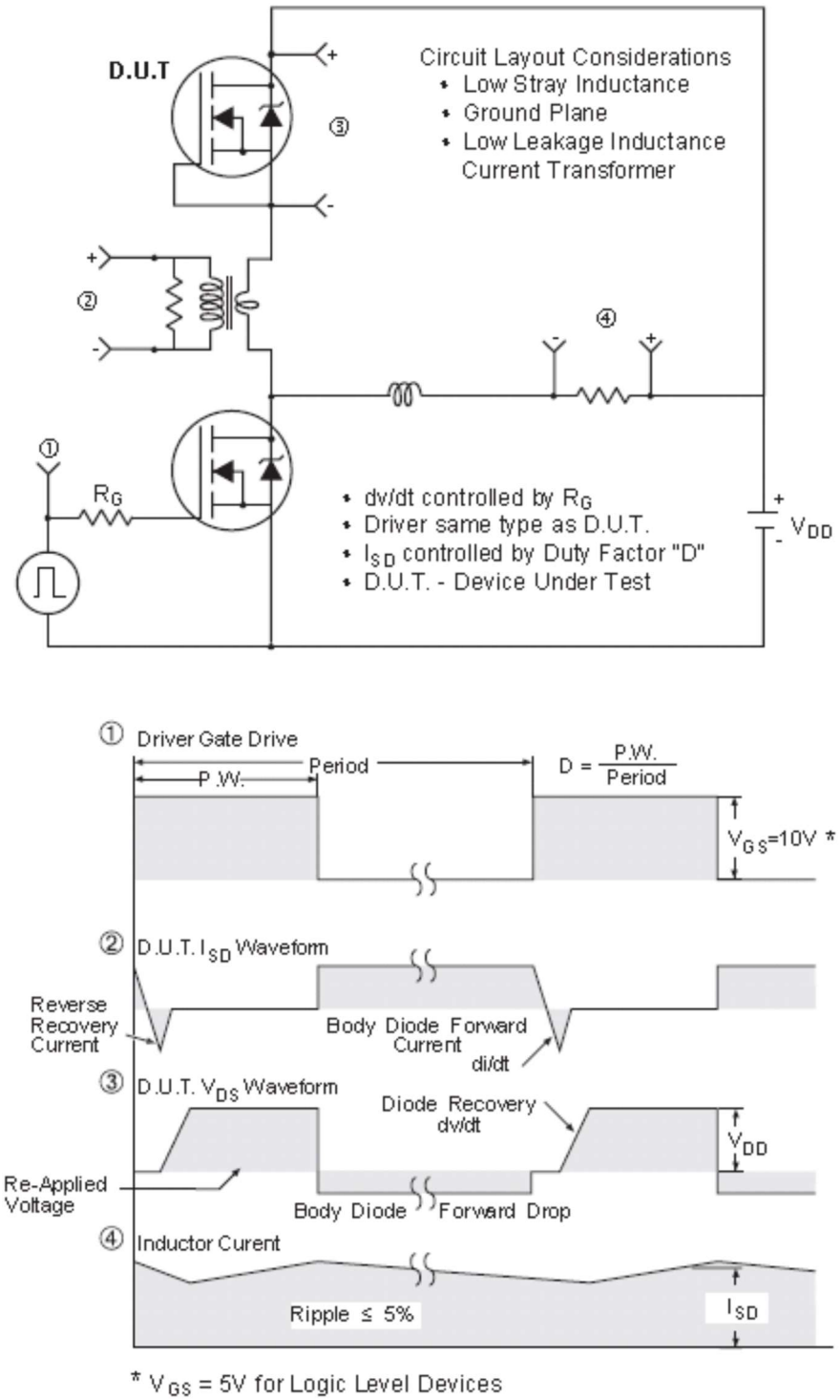
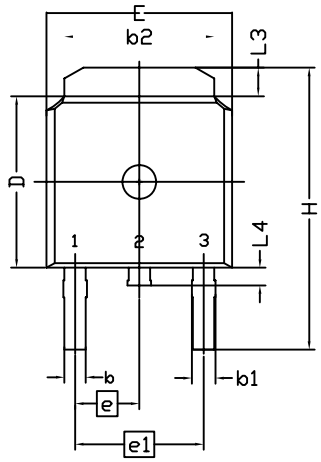
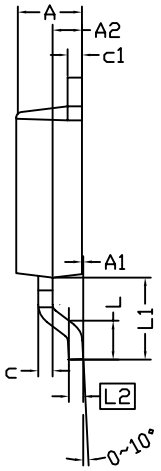
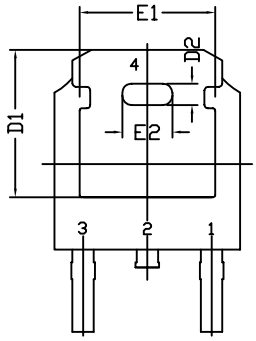


Figure 4:Peak Diode Recovery dv/dt Test Circuit & Waveforms (For N-channel)

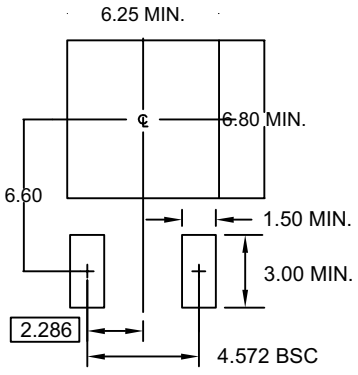
Package Mechanical Data







RECOMMENDED LAND PATTERN



UNIT: mm

SYMBOL	DIMENSION IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	2.184	2.286	2.388	0.086	0.090	0.094
A1	0.000	-----	0.127	0.000	-----	0.005
A2	0.889	1.041	1.143	0.035	0.041	0.045
b	0.635	0.762	0.889	0.025	0.030	0.035
b1	0.762	0.840	1.143	0.030	0.033	0.045
b2	4.953	5.340	5.461	0.195	0.210	0.215
c	0.450	0.508	0.610	0.018	0.020	0.024
c1	0.450	0.508	0.610	0.018	0.020	0.024
D	5.969	6.096	6.223	0.235	0.240	0.245
D1	5.210	5.249	5.380	0.205	0.207	0.212
D2	0.662	0.762	0.862	0.026	0.030	0.034
E	6.350	6.604	6.731	0.250	0.260	0.265
E1	4.318	4.826	4.901	0.170	0.190	0.193
E2	1.678	1.778	1.878	0.066	0.070	0.074
e	2.286 BSC			0.090 BSC		
e1	4.572 BSC			0.180 BSC		
H	9.398	10.033	10.414	0.370	0.395	0.410
L	1.270	1.520	2.032	0.050	0.060	0.080
L1	2.921 REF.			0.115REF.		
L2	0.408	0.508	0.608	0.016	0.020	0.024
L3	0.889	1.016	1.270	0.035	0.040	0.050
L4	0.635	-----	1.016	0.025	-----	0.040

NOTE
1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH SHOULD BE LESS THAN 6 MILS.
2. DIMENSION L IS MEASURED IN GAUGE PLANE
3. TOLERANCE 0.10 mm UNLESS OTHERWISE SPECIFIED
4. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.
5. REFER TO JEDEC TO-252 (AA)

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